

Title (en)
STONE COMPOSITE SLABS USED FOR INSULATION

Title (de)
STEINVERBUNDPLATTEN ZUR ISOLIERUNG

Title (fr)
PLAQUES COMPOSITES EN PIERRE POUR L'ISOLATION

Publication
EP 1339771 A1 20030903 (DE)

Application
EP 01984777 A 20011128

Priority
• DE 10060817 A 20001207
• EP 0113894 W 20011128

Abstract (en)
[origin: WO0246262A1] The invention relates to a method for producing composite bodies from mineral shaped bodies and foamed polyurethane layers. According to said method, the mineral shaped body is coated, in a closed mould, with a foamable polyurethane composition consisting of a polyol mixture, water, low-boiling hydrocarbons, carboxylic acids, amines, catalysts, foam stabilisers, wetting agents and dispersants, in addition to a polyisocyanate. The mould must not be preheated and during the foaming process the composition is only subjected to the inherent pressure generated in said process. In another embodiment, the foamed body is produced separately and is subsequently glued to the mineral shaped body. The composite bodies exhibit a low thermal conductivity and are suitable for use as facing slabs.

IPC 1-7
C08G 18/36; **B32B 27/40**; **B32B 5/18**; **E04C 2/26**

IPC 8 full level
B32B 5/18 (2006.01); **B32B 27/40** (2006.01); **C08G 18/30** (2006.01); **C08G 18/36** (2006.01); **C08G 18/66** (2006.01); **E04C 2/26** (2006.01); **E04F 13/14** (2006.01); **C08G 101/00** (2006.01)

CPC (source: EP US)
B32B 5/18 (2013.01 - EP US); **B32B 9/04** (2013.01 - EP US); **B32B 27/40** (2013.01 - EP US); **C08G 18/36** (2013.01 - EP US); **C08G 18/6696** (2013.01 - EP US); **E04C 2/26** (2013.01 - EP US); **E04F 13/14** (2013.01 - EP US); **C08G 2110/0025** (2021.01 - EP US); **Y10T 428/249953** (2015.04 - EP US)

Citation (search report)
See references of WO 0246262A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
WO 0246262 A1 20020613; DE 10060817 A1 20020620; EP 1339771 A1 20030903; JP 2004515584 A 20040527; US 2004115415 A1 20040617

DOCDB simple family (application)
EP 0113894 W 20011128; DE 10060817 A 20001207; EP 01984777 A 20011128; JP 2002547997 A 20011128; US 45768903 A 20030609